

Approved **THERMOSET**-polymers for Active Mold Packaging and Laser Direct Structuring with LPKF systems

THERMOSET Polymers				
Company	Compound Family	Type	Molding	CLR
Sumitomo Bakelite	EME-L	Epoxy polymer	CMPR, TRSF	BLK
	EM-L	Epoxy polymer	CMPR, TRSF, INJCT	BLK
	TM-L	Unsaturated polyester polymer	TRSF, INJCT	BLK
	PM-L	Phenolic polymer	CMPR, INJCT	BLK
Shin-Etsu	KMC-9200	Epoxy polymer	CMPR, TRSF	BLK

CMPR                - compression mold  
 TRSF               - transfer mold  
 INJCT              - injection mold

These materials were approved in cooperation between the compound suppliers and LPKF in terms of reliability, plating performance and copper adhesion strength.

For further information regarding LDS approved materials, please contact LPKF staff.

Recently added or edited materials are **highlighted in blue**.

The most recent version of this list is available here:

[Link to list of approved thermoset polymers for Active Mold Packaging & Laser Direct Structuring](#)

Approved THERMO-PLASTIC polymers for Laser Direct Structuring (LDS) with LPKF laser systems.

Thermoplastic materials				
Polymer	Company	Grade Name	CLR	
ABS	RTP	699 X 113386 B	BLK	
	Trinseo	MAGNUM™ LDS/ABS 3453	WHT	
PC/ABS	Dongsung	NEOLDS PC/ABS	BLK	
		NEOLDS PC/ABS H	BLK	
	Kingfa	Vismid 3200 LDS	BLK	
		Vismid SOL 3200 LDS	WHT	
	LG Chem	LUPOY LS 5004 BK	BLK	
	Lucky Enpla	LAY1000 9309	BLK	
	MEP		XANTAR® LDS 3710	BLK
			XANTAR® RC 3711	GRY
			XANTAR® LDS 3720	BLK
			XANTAR® LDS 3722	GRY
			XANTAR® LDS 3724	WHT
			Iupilon LAG 2710R2	WHT
			Iupilon LAG 2720R2	WHT
			Iupilon LAG 2730R	WHT
			Iupilon LAG 2910R2	BLK
			Iupilon LAG 2920R	BLK
			Iupilon LAG 2920R2	BLK
			Iupilon LAG 2930R	BLK
			RTP	
	2599 X 130952 B	WHT		
	Sabic		Thermocomp NX10302	BLK
			Thermocomp NX11302	WHT
	Sinoplast		POLYKING® HF420-LM	BLK
	Samsung SDI		LP-1010	BLK
			LP-1011	WHT
	Wah Hong		TPJF231F	BLK

Thermoplastic materials			
Polymer	Company	Grade Name	CLR
PC	Bluestar Chengrand	SUNPLAS LDS C0040	WHT
		SUNPLAS LDS C0140	BLK
	Kingfa	Vismid SOL 2100 LDS	WHT
		Vismid SOL 2102 LDS	WHT
	LG Chem	LUPOY LS1004W	WHT
		LUPOY LS1004 BK	BLK
		LUPOY LS2302W	WHT
		LUPOY LS2302 BK	BLK
	Lucky Enpla	LPC1000 9321	BLK
		LPC1001 9306	BLK
	MEP	XANTAR® LDS 3730	BLK
		XANTAR® LDS 3732	GRY
		XANTAR® LDS 3750	BLK
		XANTAR® LDS 3760	BLK
		XANTAR® LDS 3764	WHT
		XANTAR® LDS 3734	WHT
		Iupilon MTB100R 8920F	BLK
	RTP	399 X 113385 B	BLK
		399 X 131442 K	BLK
	Samsung SDI	LP-1020	BLK
		LP-1021	WHT
		LP-3200	BLK
		LP-3201	WHT
		LP-3300	BLK
	Sabic	LNP™ THERMOCOMP™ COMPOUND D10001VR	BLK
		<b>LNP™ THERMOCOMP™ COMPOUND D10001VI</b>	<b>DIV</b>
		LNP™ THERMOCOMP™ COMPOUND D10006VR	BLK
		LNP™ THERMOCOMP™ COMPOUND DF002FV	DIV
		<b>LNP™ THERMOCOMP™ COMPOUND DF002FVQ</b>	<b>BLK</b>
		LNP™ THERMOCOMP™ COMPOUND DF0041VI	BLK
		<b>LNP™ THERMOCOMP™ COMPOUND DF0061VI</b>	<b>BLK</b>
		LNP™ THERMOCOMP™ COMPOUND DX13354X	DIV
		LNP™ THERMOCOMP™ COMPOUND DX15354	BLK
		LNP™ THERMOCOMP™ COMPOUND DX11354	BLK
		LNP™ THERMOCOMP™ COMPOUND DX11354X	WHT
		LNP™ THERMOCOMP™ COMPOUND DX11355	BLK
		LNP™ THERMOCOMP™ COMPOUND DX13354	BLK
		LNP™ THERMOCOMP™ COMPOUND DX14354X	WHT
	Sinoplast	POLYKING® 6010-LM/BK	BLK
		POLYKING® 6010-LMT/WH	WHT
		POLYKING® 7015-LM	BLK
POLYKING® 7015-LMT		WHT	
Trinseo	EMERGE LDS/PC 8900	BLK	

Thermoplastic materials			
Polymer	Company	Grade Name	CLR
PC	PolyOne	Edgetek™ ET3200-8177 LDS NHFR BK002	BLK
		Edgetek™ ET3200-8205 LDS NHFR BK001	BLK
PC+PET	MEP	XANTAR® LDS 3780	BLK
PA/PPA	DSM	ForTii™ LDS51B	GRY
		ForTii™ LDS81	BLK
		ForTii™ LDS85	GRY
		ForTii™ LDS85B	BLK
		ForTii™ Eco LDS61	BLK
		ForTii™ Eco LDS62	BLK
	EMS	Grilamid 1SBVX-50H LDS	BLK
		Grilamid FE10902 black	BLK
		Grilamid 1S XE 11382 LDS	BLK
		Grilamid 2S XE 11397 LDS	BLK
		Grivory HT XE 11015 LDS black 9511	BLK
	Ensinger	TECACOMP® PPA LDS black 1014979 (Thermal conductive)	BLK
		TECACOMP® PPA LDS black 1014980 (Thermal conductive)	BLK
	Evonik	Vestamid® HT <i>plus</i> LDS 1031 black	BLK
		Vestamid® HT <i>plus</i> LDS 3031 black	BLK
	Kingfa	Vismid SOL 65250 LDS	BLK
	MEP	Reny 1002PS	BLK
		Reny 1501PS	BLK
		Reny XHP 1002	BLK
		<b>Reny XHP 1002 A</b>	<b>BLK</b>
		Reny XHP 1005	GRY
		Reny XHP 1081L	BLK
		Reny XHP 1351L	BLK
		Reny XHP 1501	BLK
		Reny XHP 2091L	BLK
		Reny XHP 2082 ET (Thermal conductive)	WHT
		Reny XHP 2084 ET (Thermal conductive)	WHT
		PTS	CREAMID-A3H2G7LDS*M9200
	CREAMID-AH2GX5ELDS*M9200		BLK
	Polyone	Therma-Tech™ TT6000-8709 EI LDS (Thermal conductive)	BLK
	RTP	RTP 299 X 113399 H	BLK
		RTP 4099 X 117359 D	BLK
RTP 4099 A X 117387		BLK	

Thermoplastic materials			
Polymer	Company	Grade Name	CLR
PA/PPA	Sabic	LNP™ THERMOCOMP™ COMPOUND UF 0067V	BLK
		UX08325	BLK
		UX08305	BLK
	Sinoplast	POLYKING® HT-LM	BLK
PBT	Evonik	Vestodur® X9423	BLK
	RTP	1099 X 127271 C	BLK
	Sinoplast	POLYKING® BT201-LMG6	BLK
COP	Zeon	Zeonex RS-420 LDS	BLK
PPO	Bluestar Chengrand	CP003-LDS	WHT
		CP013-LDS	BLK
	Sabic	LNP™ THERMOCOMP™ COMPOUND Z1C00VI	BLK
PPE	Premix	Preperm 260 LDS	BLK
LCP	PolyOne	Edgetek™ ET9600-8010 LDS BK001	BLK
	Ensinger	TECACOMP® LCP LDS black 1014978	BLK
		TECACOMP® LCP LDS black 1049426	BLK
	RTP	RTP 3499-3 X 113393 A	GRY
	Celanese	Vectra® E840i LDS	GRY
		Vectra® E845i LDS	GRY
	Sabic	LNP™ THERMOCOMP™ COMPOUND 8K008V	BLK
		LNP™ THERMOCOMP™ COMPOUND 8KF44VE	BLK
		LNP™ THERMOCOMP™ COMPOUND 8MF44VG	BLK
	Seyang Polymer	Seyang® LCP G825GT LS	BLK
Sinoplast	POLYKING® C301-LM/BK	BLK	
Otsuka Chemical	POTICON® VCW8B-LDS	GRY	
PEI	RTP	2199 X 127272 A	BLK
		2199 X 127272 E	BLK
PEEK	Ensinger	TECACOMP® PEEK LDS black 1017665	BLK

These materials were approved by LPKF in terms of plating performance and adhesion (peel) strength.

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[Link to list of approved thermoplastic polymers for 3D MID and Laser Direct Structuring](#)